# 3GPP TSG-CN Meeting #25 8<sup>th</sup> – 10<sup>th</sup> September 2004. Palm Springs, USA.

Source:	CN3
Title:	WID for DIAMETER on the GGSN Gi interface
Agenda item:	10.1
Document for:	APPROVAL

## **Work Item Description**

# Title

# **DIAMETER on the GGSN Gi interface**

### 1 3GPP Work Area

	Radio Acce	ess						
Х	Core Network							
	Services							
2	Linked work items							
	No	one						
3	Ju	stificat	ion					
		hat coul					US protocol. Other to use Diameter in the	
		s used o	on a multitue	de of interfa	ces including C	k, Sh, Gq, Ro, Rf,	in IMS, policy control and	
4	Ot	ojective						
	Diameter s	hould b	e specified	also for use	on the Gi interfa	ce.		
5	Service Aspects							
	None							
6	MMI-Aspects							
	None							
7	Charging Aspects							
		one						
8	Se	curity /	Aspects					
	No	one						
9	Im	pacts						
Affects	s: UICC	ME	AN	CN	Others			

Affects:	apps	ME	AN	CN	Others
Yes				Х	
No	Х	Х	Х		Х
Don't					
know					

#### Expected Output and Time scale (to be updated at each plenary)

	New specifications							
Spec No.	Title		Prime rsp. WG	2ndaryPresented forrsp.information atWG(s)plenary#		Approved at plenary#	Comments	
			Affe	cted existi	ina s	specificatio	ons	
Spec No.	CR	Subject			_	Approved at		Comments
TS 29.061		Provision AAA information over Diameter transport				CN#29 (S	ept.2005)	Add Diameter support to Gi interface
					_			

### 11 Work item raporteurs

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### 12 Work item leadership

CN3

#### 13 Supporting Companies

T-Mobile, Cisco Systems, Nortel Networks, Siemens

#### 14 Classification of the WI (if known)

	Feature (go to 14a)
Х	Building Block (go to 14b)
	Work Task (go to 14c)

14a The WI is a Feature: List of building blocks under this feature

14b The WI is a Building Block: parent Feature (TEI-7)

14c The WI is a Work Task: parent Building Block